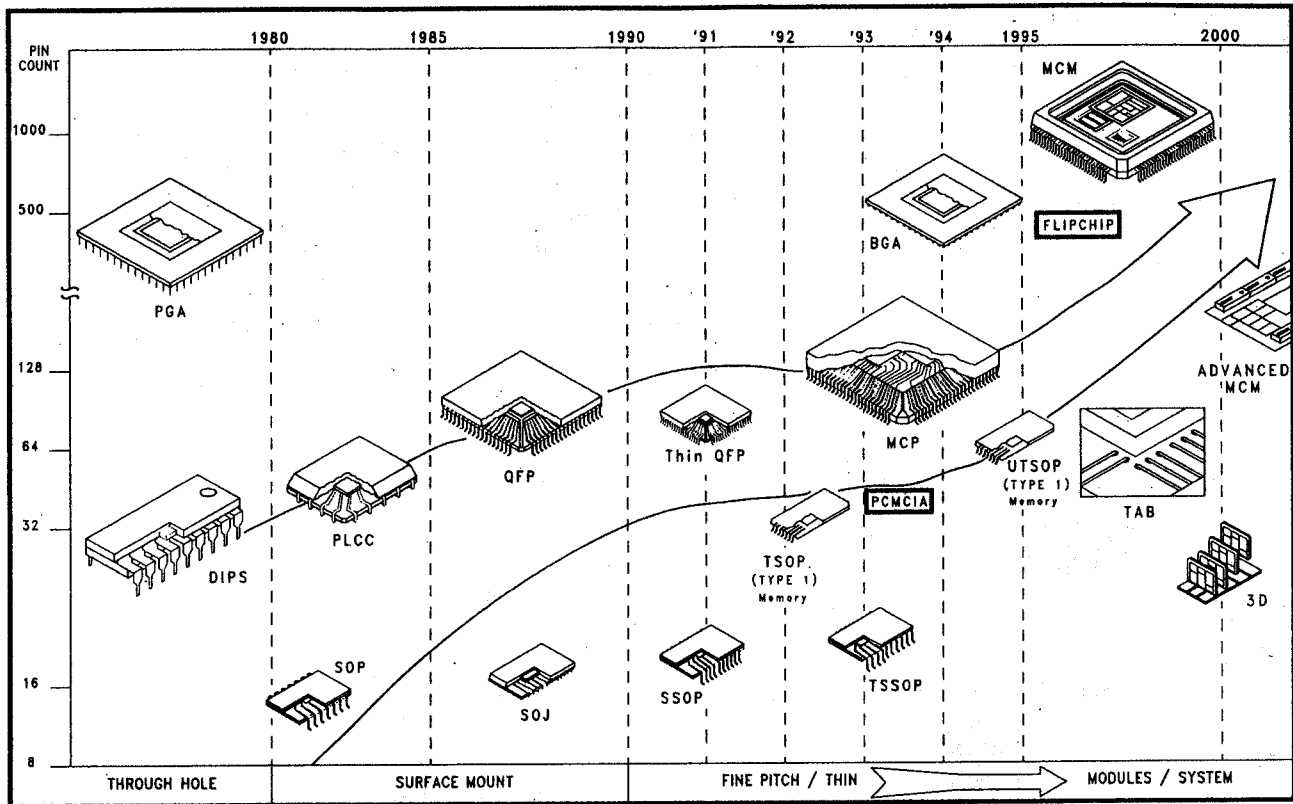




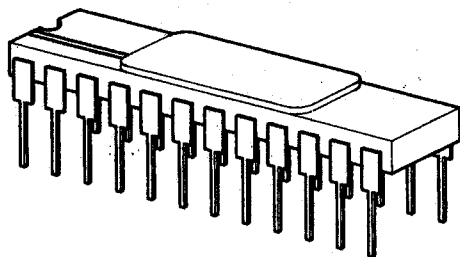
PACKAGE TECHNOLOGY ROAD MAP



TL/P/11824-1

Package Configuration

Ceramic Sidebrazed Dual-In-line Package (SB)

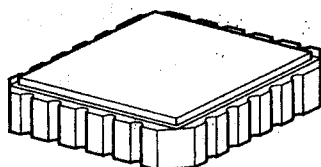


TL/P/11794-1

Package Characteristics

- Through Hole Package
- Brazed Straight Leads to Pads on Package Side
- Gold Plate or Solder Dip Lead Finish
- Multilayer Ceramic Package
- Solder Seal
- Footprint Compatible with Cerdip and MDIP

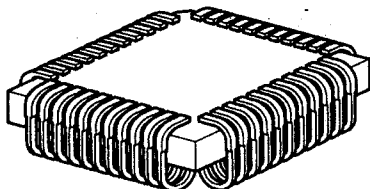
Ceramic Leadless Chip Carrier (LCC)



TL/P/11794-2

- Surface/Socket Mount Package
- Terminal Pads Instead of Leads
- Gold Plate or Solder Dip Lead Finish
- Multilayer Ceramic Package
- Solder Seal
- Footprint Compatible with CQJB and PLCC

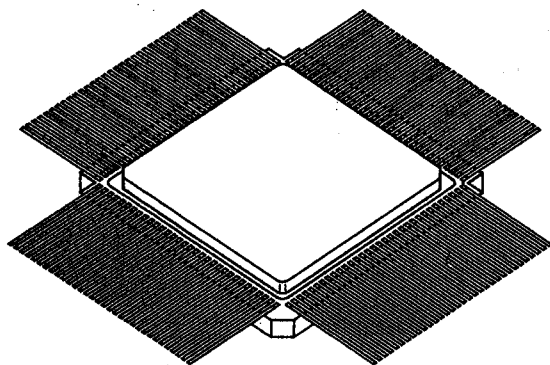
Ceramic Quad J-Bend (CQJB)



TL/P/11794-3

- Surface Mount Package
- J-Bend Lead Configuration
- Gold Plate Lead Finish
- Multilayer Ceramic Package
- Solder Seal
- Footprint Compatible with LCC and PLCC

Ceramic Quad Flatpack (CQFP)



TL/P/11794-4

- Surface Mount Package
- Straight Lead Configuration
- Gold Plate Lead Finish
- Multilayer Ceramic Package
- Solder Seal

Ceramic Flatpack

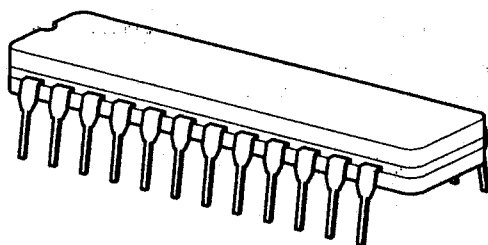


TL/P/11794-5

- Surface Mount or Through Hole Package
- Straight Lead Configuration
- Gold Plate Lead Finish
- Multilayer Ceramic Package
- Solder Seal
- Footprint Compatible with Cerpac

Package Configuration (Continued)

Ceramic Dual-In-Line Package (Cerdip)

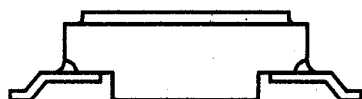


TL/P/11794-6

Package Characteristics (Continued)

- Through Hole Package
- Straight Lead Configuration
- Solder Dip Lead Finish
- Pressed Ceramic Package
- Glass Seal
- Footprint Compatible with SB and MDIP

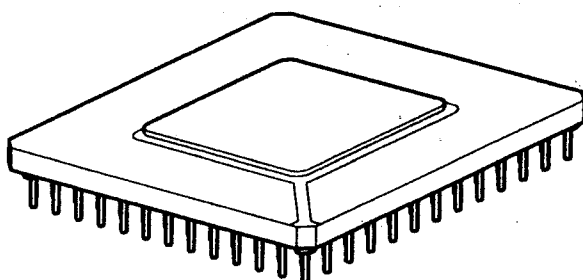
Ceramic Small Outline Package



TL/P/11794-7

- Surface Mount Package
- Gull Wing Lead Configuration
- Gold Plate Lead Finish
- Multilayer Ceramic Package
- Solder Seal
- Footprint Compatible with Wide Body Plastic SOP

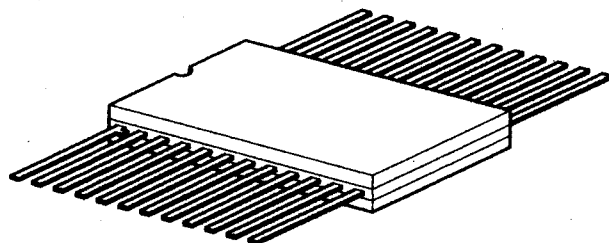
Ceramic Pin Grid Array (CPGA)



TL/P/11794-8

- Through Hole Package
- Straight Lead Configuration
- Gold Plate Lead Finish
- Multilayer Ceramic Package
- Solder Seal
- Footprint Compatible with PPGA

Cerpack

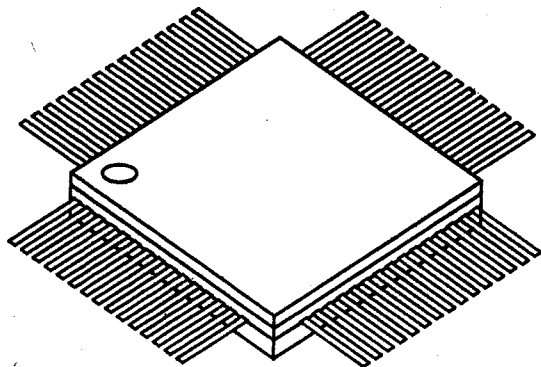


TL/P/11794-9

- Surface Mount or Through Hole Package
- Straight Lead Configuration
- Solder Dip Lead Finish
- Pressed Ceramic Package
- Glass Seal
- Footprint Compatible with Flatpak

Package Configuration (Continued)

Cerquad

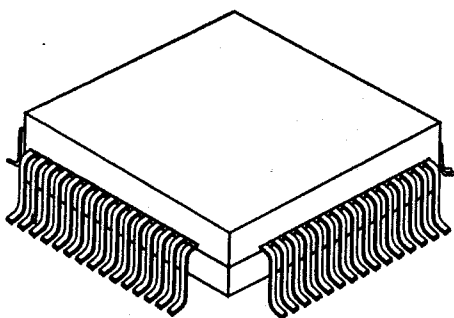


TL/P/11794-10

Package Characteristics (Continued)

- Surface Mount Package
- Straight Lead Configuration
- Solder DIP or Tin Plate Lead Finish
- Pressed Ceramic Package
- Glass Seal
- Footprint Compatible with PQFP
- Can be Electrically and/or Thermally Enhanced

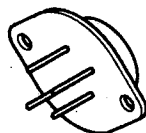
Cerquad—EIAJ



TL/P/11794-11

- Surface Mount Package
- Gull Wing Lead Configuration
- Solder DIP or Tin Plate Lead Finish
- Pressed Ceramic Package
- Glass Seal
- Footprint Compatible with PQFP
- Can be Electrically and/or Thermally Enhanced

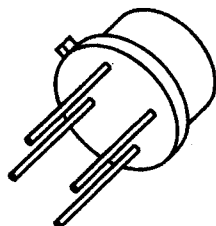
**TO-3
Metal Can**



TL/P/11794-12

- Through Hole Package
- Solder Dip Lead Finish
- Steel or Aluminum Base
- Compression Glass Seal

**TO-5 and TO-39
Metal Can**

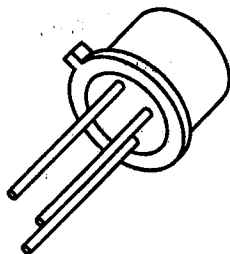


TL/P/11794-13

- Through Hole Package
- Solder Dip or Gold Plate Lead Finish TO-5
- Kovar Base
- Matched Glass Seal TO-39
- Kovar or Steel Base
- Matched or Compression Glass Seal

Package Configuration (Continued)

**TO-18
Metal Can**

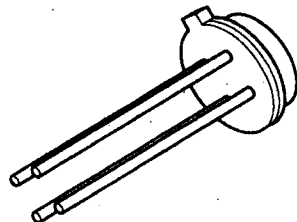


TL/P/11794-14

Package Characteristics (Continued)

- Through Hole Package
- Solder DIP or Gold Plate Lead Finish
- Kovar Base
- Matched Glass Seal

**TO-46, TO-52 and TO-72
Metal Can**



TL/P/11794-15

- Through Hole Package
- Solder Dip or Gold Plate Lead Finish
- Kovar or Steel Base
- Matched or Compression Glass Seal